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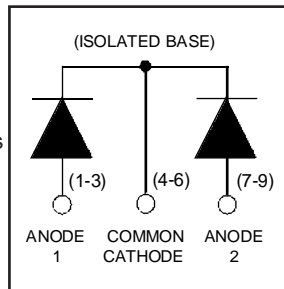
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# HFA75MB40C

Ultrafast, Soft Recovery Diode

## Features

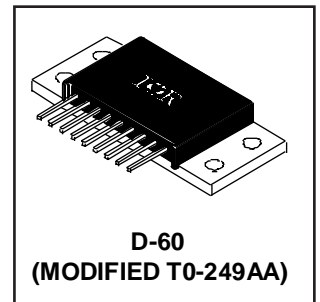
- Reduced RFI and EMI
- Reduced Snubbing
- Extensive Characterization of Recovery Parameters



$V_R = 400V$
$V_F(\text{typ.})^{\text{Ⓢ}} = 1V$
$I_{F(AV)} = 75A$
$Q_{rr}(\text{typ.}) = 200nC$
$I_{RRM}(\text{typ.}) = 6A$
$t_{rr}(\text{typ.}) = 30ns$
$di_{(rec)M}/dt(\text{typ.})^{\text{Ⓢ}} = 190A/\mu s$

## Description

HEXFRED™ diodes are optimized to reduce losses and EMI/RFI in high frequency power conditioning systems. An extensive characterization of the recovery behavior for different values of current, temperature and di/dt simplifies the calculations of losses in the operating conditions. The softness of the recovery eliminates the need for a snubber in most applications. These devices are ideally suited for power converters, motors drives and other applications where switching losses are significant portion of the total losses.



## Absolute Maximum Ratings (per Leg)

	Parameter	Max.	Units
$V_R$	Cathode-to-Anode Voltage	400	V
$I_F @ T_C = 25^\circ C$	Continuous Forward Current	75	A
$I_F @ T_C = 100^\circ C$	Continuous Forward Current	36	
$I_{FSM}$	Single Pulse Forward Current ①	300	
$I_{AS}$	Maximum Single Pulse Avalanche Current ②	5.0	mJ
$E_{AS}$	Non-Repetitive Avalanche Energy ②	1.4	
$P_D @ T_C = 25^\circ C$	Maximum Power Dissipation	125	W
$P_D @ T_C = 100^\circ C$	Maximum Power Dissipation	50	
$T_J$	Operating Junction and	-55 to +150	°C
$T_{STG}$	Storage Temperature Range		
	Soldering Temperature, for 10 sec.	300 (0.063 in. (1.6mm) from case)	

## Thermal - Mechanical Characteristics

	Parameter	Min.	Typ.	Max.	Units
$R_{\theta JC}$	Junction-to-Case, Single Leg Conducting	----	----	1.0	°C/W
	Junction-to-Case, Both Legs Conducting	----	----	0.50	K/W
$R_{\theta CS}$	Case-to-Sink, Flat, Greased Surface	----	0.10	----	
$Wt$	Weight	----	58 (2.0)	----	g (oz)
	Mounting Torque	35 (4.0)	----	50 (5.7)	lbf·in (N·m)

**Note:** ① Limited by junction temperature  
 ② L = 100μH, duty cycle limited by max  $T_J$   
 ③ 125°C

# HFA75MB40C

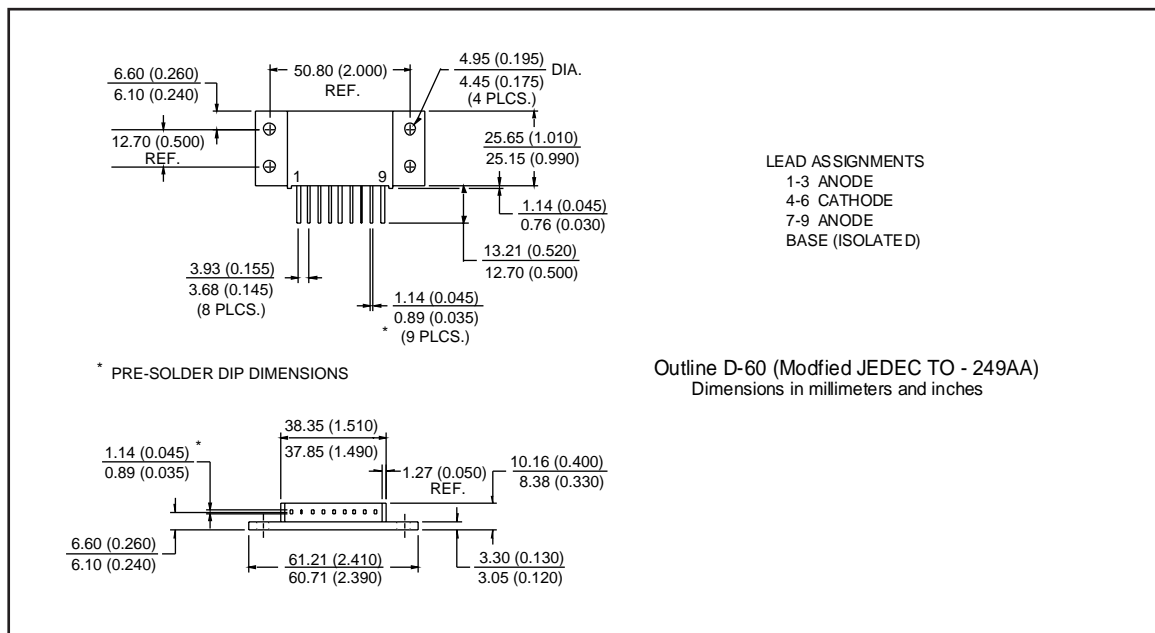
International  
**IOR** Rectifier

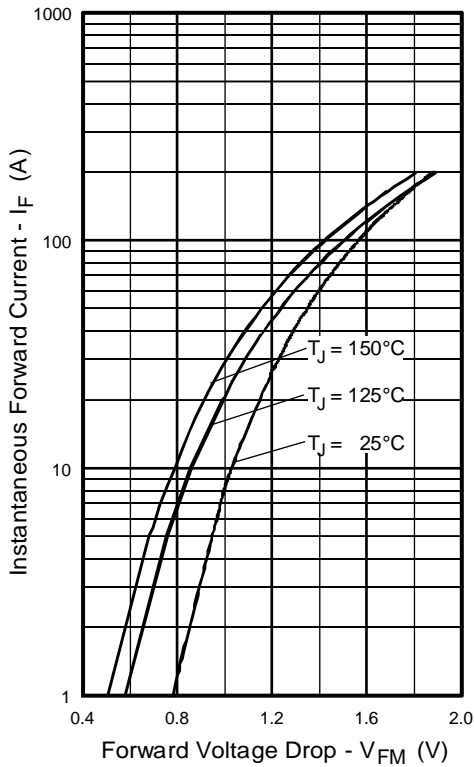
## Electrical Characteristics (per Leg) @ T<sub>J</sub> = 25°C (unless otherwise specified)

	Parameter	Min.	Typ.	Max.	Units	Test Conditions
V <sub>BR</sub>	Cathode Anode Breakdown Voltage	400	—	—	V	I <sub>R</sub> = 100μA
V <sub>FM</sub>	Max Forward Voltage	—	1.1	1.3	V	I <sub>F</sub> = 35A
		—	1.3	1.5		I <sub>F</sub> = 75A
		—	1.0	1.2		I <sub>F</sub> = 35A, T <sub>J</sub> = 125°C
I <sub>RM</sub>	Max Reverse Leakage Current	—	0.50	3.0	μA	V <sub>R</sub> = V <sub>R</sub> Rated
		—	0.75	4.0	mA	T <sub>J</sub> = 125°C, V <sub>R</sub> = 320V
C <sub>T</sub>	Junction Capacitance	—	90	125	pF	V <sub>R</sub> = 200V
L <sub>S</sub>	Series Inductance	—	9.2	—	nH	Lead to lead 5mm from package body

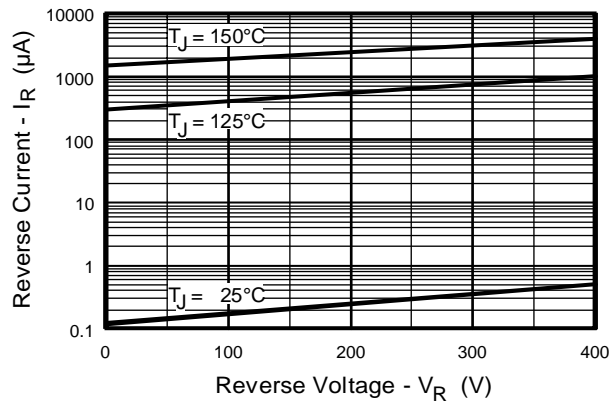
## Dynamic Recovery Characteristics (per Leg) @ T<sub>J</sub> = 25°C (unless otherwise specified)

	Parameter	Min.	Typ.	Max.	Units	Test Conditions
t <sub>rr</sub>	Reverse Recovery Time	—	30	—	ns	I <sub>F</sub> = 1.0A, di <sub>F</sub> /dt = 200A/μs, V <sub>R</sub> = 30V
t <sub>rr1</sub>		—	67	100		T <sub>J</sub> = 25°C
t <sub>rr2</sub>		—	110	170		T <sub>J</sub> = 125°C
I <sub>RRM1</sub>	Peak Recovery Current	—	6.0	11	A	T <sub>J</sub> = 25°C
I <sub>RRM2</sub>		—	9.0	16		T <sub>J</sub> = 125°C
Q <sub>rr1</sub>	Reverse Recovery Charge	—	200	540	nC	T <sub>J</sub> = 25°C
Q <sub>rr2</sub>		—	500	1300		T <sub>J</sub> = 125°C
di <sub>(rec)M</sub> /dt1	Peak Rate of Fall of Recovery Current	—	240	—	A/μs	T <sub>J</sub> = 25°C
di <sub>(rec)M</sub> /dt2		During t <sub>b</sub>	—	190		—

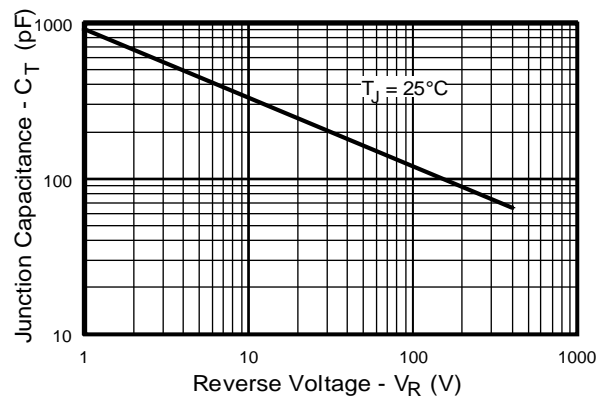




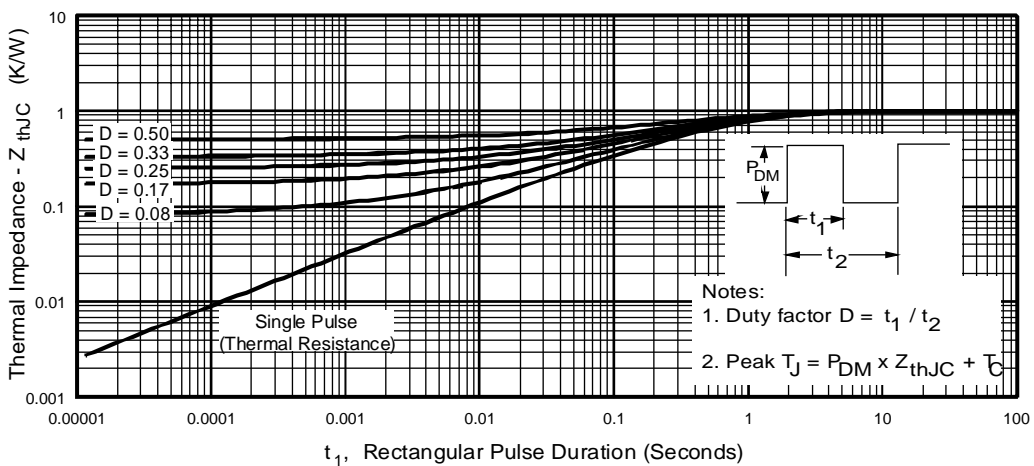
**Fig. 1** - Maximum Forward Voltage Drop vs. Instantaneous Forward Current, (per Leg)



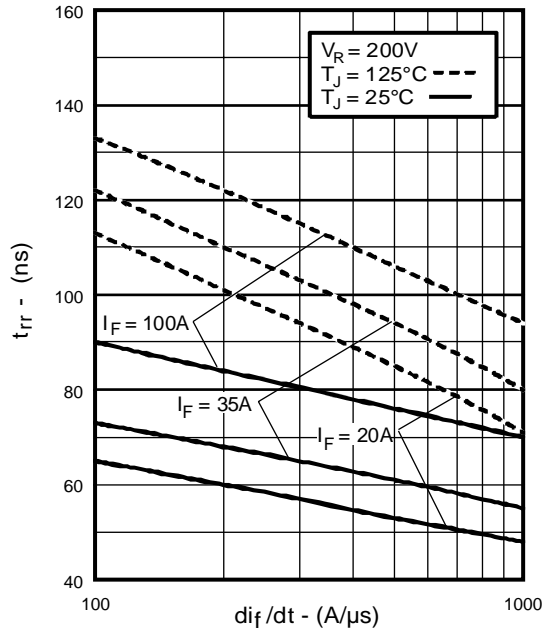
**Fig. 2** - Typical Reverse Current vs. Reverse Voltage, (per Leg)



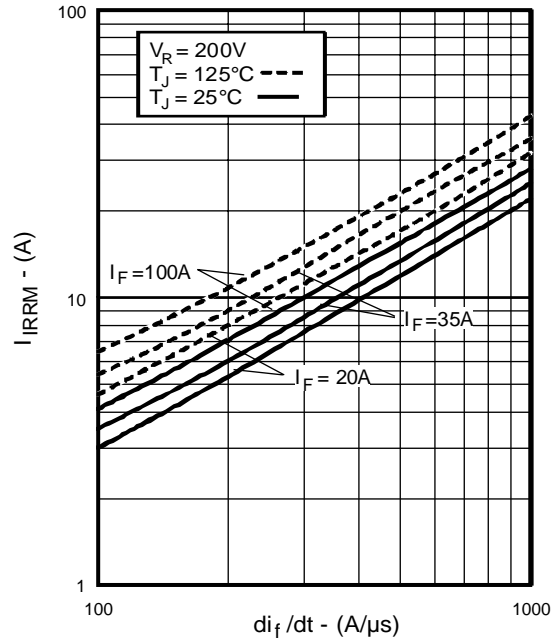
**Fig. 3** - Typical Junction Capacitance vs. Reverse Voltage, (per Leg)



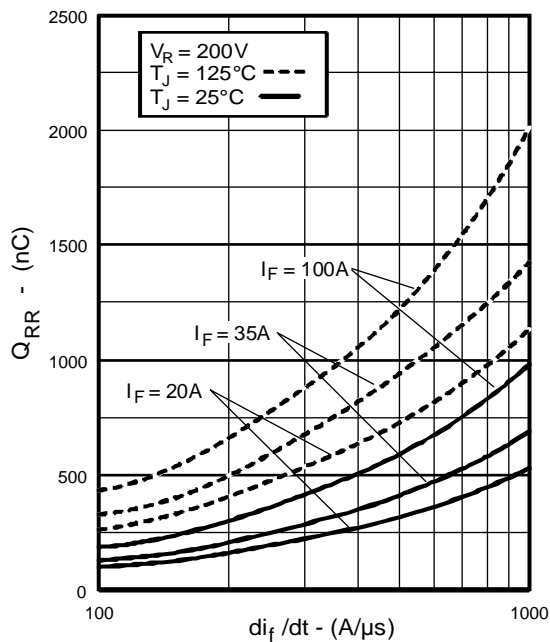
**Fig. 4** - Maximum Thermal Impedance  $Z_{thjc}$  Characteristics, (per Leg)



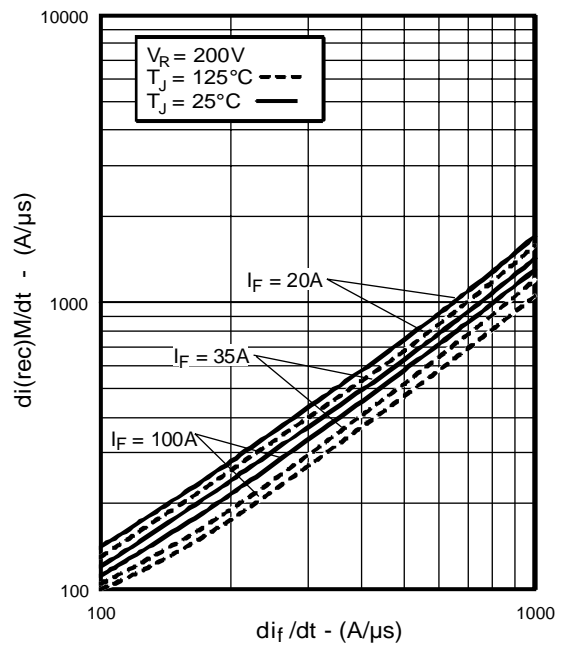
**Fig. 5 - Typical Reverse Recovery vs.  $di_f/dt$ , (per Leg)**



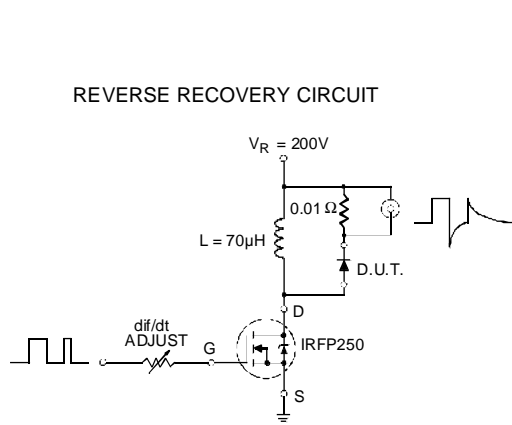
**Fig. 6 - Typical Recovery Current vs.  $di_f/dt$ , (per Leg)**



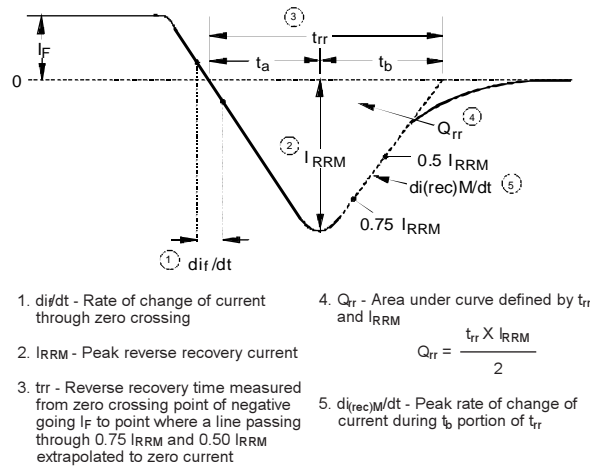
**Fig. 7 - Typical Stored Charge vs.  $di_f/dt$ , (per Leg)**



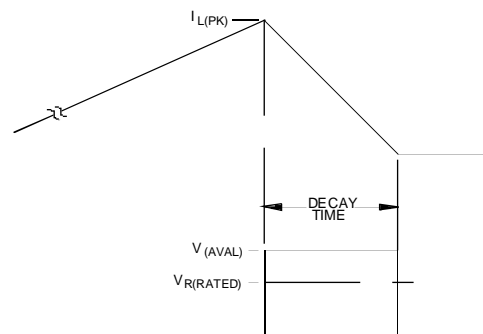
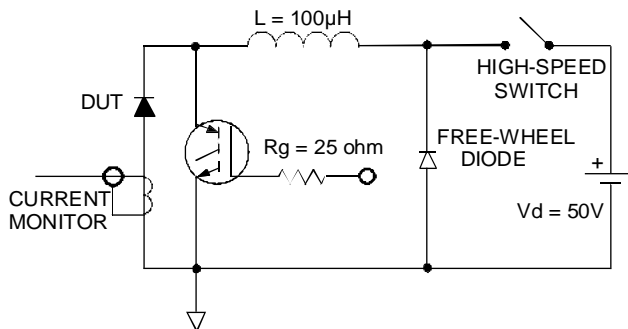
**Fig. 8 - Typical  $di_{(rec)M}/dt$  vs.  $di_f/dt$ , (per Leg)**



**Fig. 9 - Reverse Recovery Parameter Test Circuit**



**Fig. 10 - Reverse Recovery Waveform and Definitions**



**Fig. 11 - Avalanche Test Circuit and Waveforms**